TRAILING EDGE PRODUCT - MINIMUM ORDER APPLIES

1M x 8 SRAM SIL MODULE

SYS81000RKXB - 85/10/12

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Description

The SYS81000RKXB is a plastic 8M Static RAM Module housed in a standard 36 pin Single In- Line package organised as 1M x 8. This offers an extremely high PCB packing density.

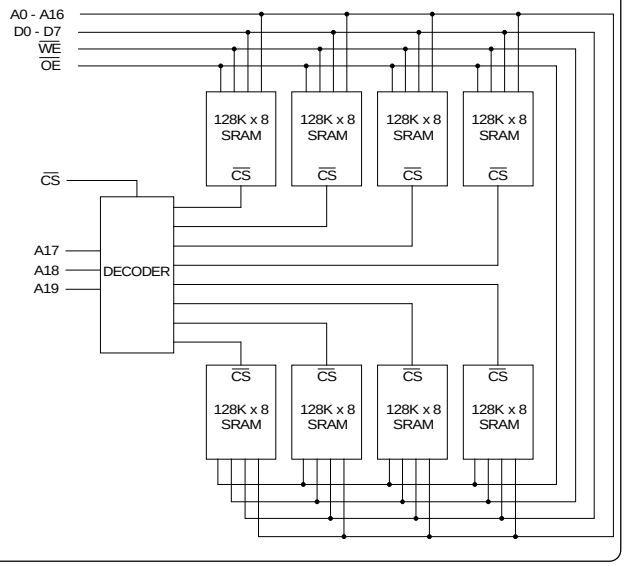
The module is constructed using eight 128Kx8 SRAMs in TSOP packages mounted onto both sides of an FR4 epoxy substrate. Access times are 85, 100 and 120ns.

The SYS81000RKXB is offered in standard and low power versions, with the -L module having a low voltage data retention mode for battery backed applications.

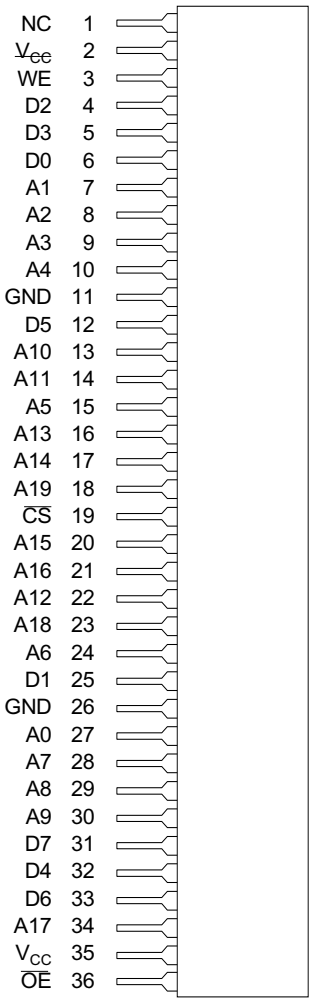
Features

- Access Times of 85/100/120ns.
- 36 Pin Industry Standard Single-In-Line package.
- 5 Volt Supply ± 10%.
- Low Power Dissipation 100/120ns :
  Average (min cycle) 501 mW (max).
  Standby (CMOS, -L) 4.4mW (max).
- Low Voltage V_{CC} Data Retention.
- Directly TTL Compatible.
- On-board Decoding & Capacitors.
- Upgradeable.

Block Diagram



Pin Definition



Pin Functions

Address Inputs	**A0 ~ A19**
Data Input/Output	**D0 ~ D7**
Chip Select Input	**$\overline{CS}$**
Read/Write Input	**$\overline{WE}$**
Output Enable Input	**$\overline{OE}$**
No Connect	**NC**
Power (+5V)	**V_{CC}**
Ground	**GND**

DC OPERATING CONDITIONS

Absolute Maximum Ratings

Voltage on any pin relative to V_{SS}	V_T	-0.5V to +7.0	V
Power Dissipation	P_T	700	mW
Storage Temperature	T_{STG}	-55 to +125	°C

Notes : (1) Stresses above those listed may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

		min	*typ*	*max*		
Supply Voltage	V_{CC}	4.5	5.0	5.5	V	
Input High Voltage	V_{IH}	2.2	-	V_{CC}+0.3	V	
Input Low Voltage	V_{IL}	-0.3	-	0.8	V	
Operating Temperature	T_A	0	-	70	°C	
	T_{AI}	-40	-	85	°C	(I)

DC Electrical Characteristics

(Vcc = 5V+/- 10%, T_A=0 to 70°C)

Parameter		*Sym*	*Test Condition*	*min*	*typ(1)*	*max*	*Unit*
I/P Leakage Current	A0~A16, $\overline{OE}$, $\overline{WE}$	I_{LI1}	0V - V_{IN} - V_{CC}	-8	-	8	µA
I/P Leakage Current	A17~A19, $\overline{CS}$	I_{LI2}	0V - V_{IN} - V_{CC}	-1	-	1	µA
Output Leakage Current	D0~D7	I_{LO}	$\overline{CS}$ = V_{IH}, $V_{I/O}$ = GND to V_{CC}	-8	-	8	µA
Average Supply Current		I_{CC}	$\overline{CS}$ = V_{IL}, V_{IN} = V_{IL}/V_{CC}-2.1V	-	52	91	mA
Standby Supply Current	TTL levels	I_{SB}	$\overline{CS}$ = V_{IH}, A17~A19 = V_{IH} or V_{IL}	-	8	24	mA
	-L, CMOS levels	I_{SB1}	$\overline{CS}$ = V_{CC}-0.2V, A17~A19 = V_{CC}-0.2V or 0.2V	-	-	0.8	mA
Output Low Voltage		V_{OL}	I_{OL} = 2.1mA	-	-	0.4	V
Output High Voltage		V_{OH}	I_{OH} = -1.0mA	2.4	-	-	V

(1) Typical values are at V_{CC} = 5.0V, T_A= 25°C and specified loading.

Capacitance

(Vcc = 5V+/- 10%,T_A=25°C)

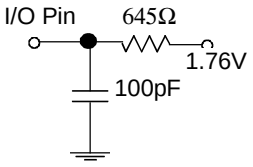
Parameter	*Symbol*	*Test Condition*	*typ*	*max*	*Unit*
Input Capacitance ($\overline{CS}$, A17~A19)	C_{IN1}	V_{IN} = 0V	-	10	pF
Input Capacitance (other)	C_{IN2}	V_{IN} = 0V	-	64	pF
I/O Capacitance	$C_{I/O}$	$V_{I/O}$ = 0V	-	80	pF

Capacitance calculated, not measured

AC Test Conditions

* Input pulse levels: V_{SS} to 3.0V
* Input rise and fall times: 5ns
* Input and Output timing reference levels: 1.5V
* Output load: see diagram
* V_{CC} = 5V± 10%

Output Load



AC OPERATING CONDITIONS

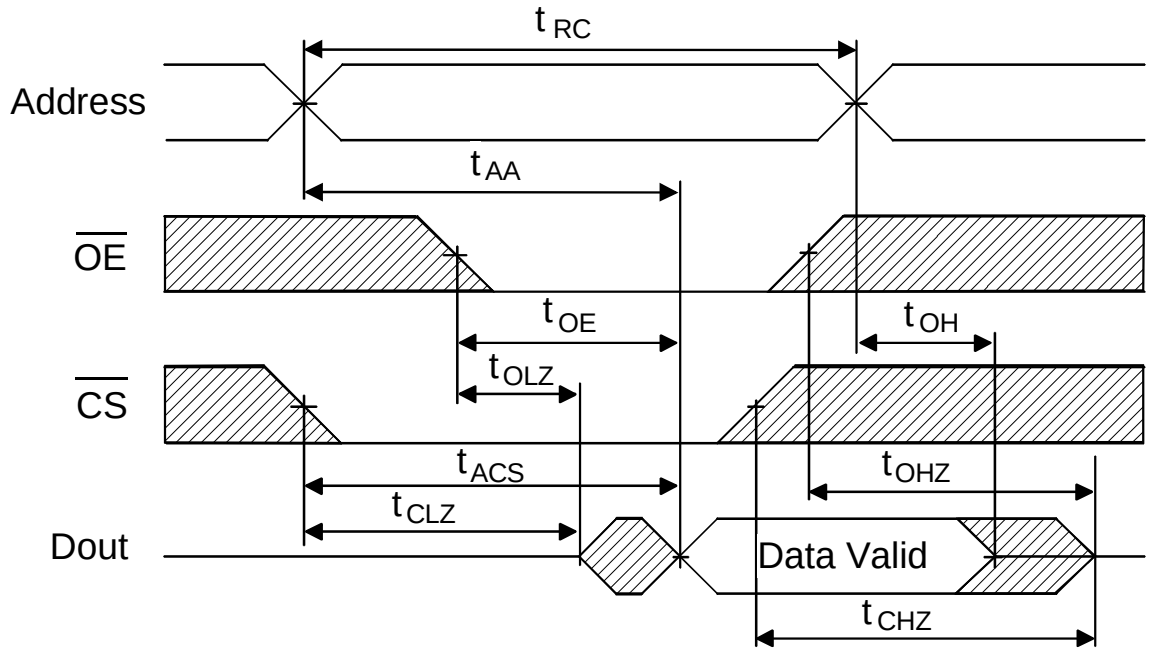
Read Cycle (1,2)

Parameter	Symbol	-85 min	-85 max	-10 min	-10 max	-12 min	-12 max	Unit
Read Cycle Time	t_{RC}	85	-	100	-	120	-	ns
Address Access Time	t_{AA}	-	85	-	100	-	120	ns
Chip Select Access Time	t_{ACS}	-	85	-	100	-	120	ns
Output Enable to Output Valid	t_{OE}	-	45	-	50	-	60	ns
Output Hold from Address Change	t_{OH}	10	-	10	-	10	-	ns
Chip Selection to Output in Low Z (2)	t_{CLZ}	10	-	10	-	10	-	ns
Output Enable to Output in Low Z (2)	t_{OLZ}	5	-	5	-	5	-	ns
Chip Deselection to O/P in High Z (2)	t_{CHZ}	0	30	0	35	0	40	ns
Output Disable to Output in High Z (2)	t_{OHZ}	0	30	0	35	0	40	ns

Notes (1) $\overline{WE}$ is High for Read Cycle.

(2) t_{HZ} and t_{OHZ} are defined as the time at which the outputs achieve open circuit conditions and are not referenced to output voltage levels.These parameters are sampled and not 100% tested.

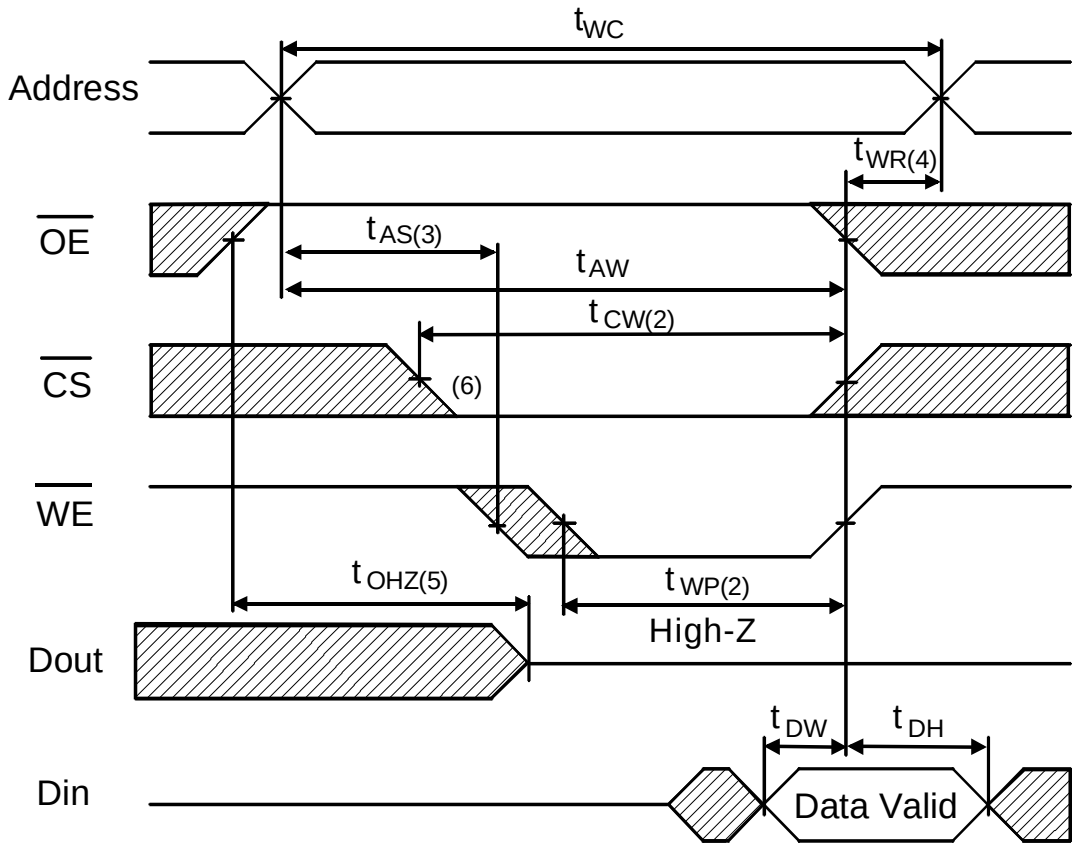
Read Cycle Timing Waveform (1,2)



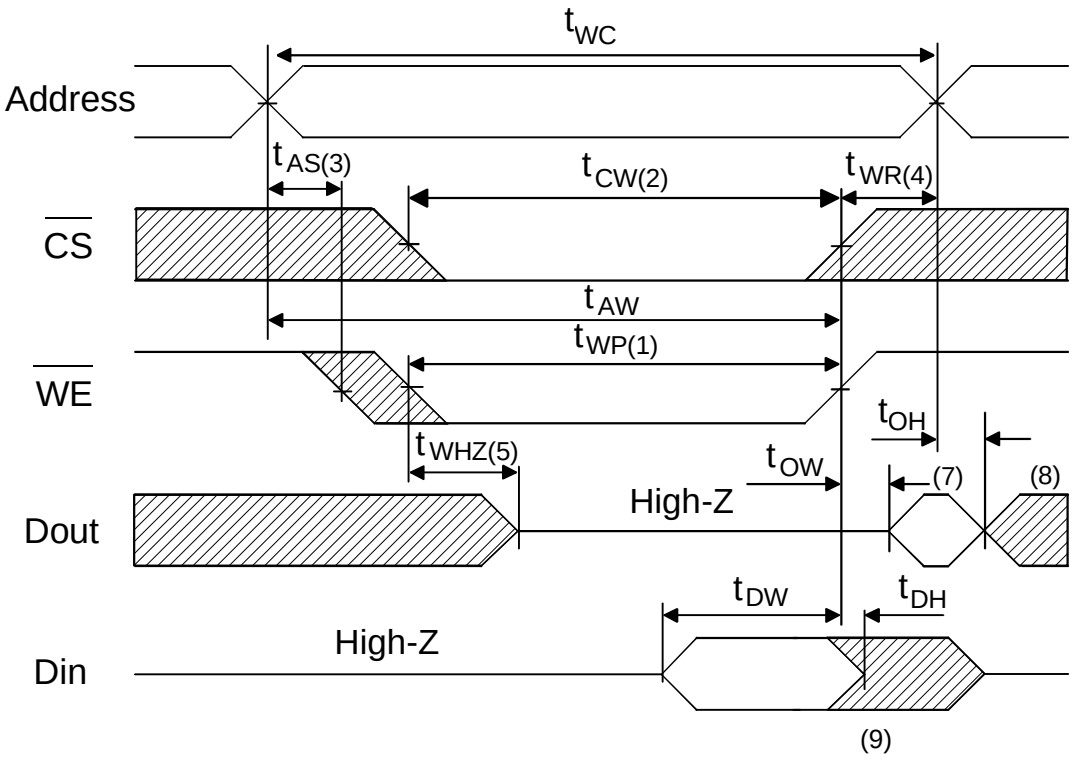
Write Cycle

Parameter	Symbol	-85 min	-85 max	-10 min	-10 max	-12 min	-12 max	Unit
Write Cycle Time	t_{WC}	85	-	100	-	120	-	ns
Chip Selection to End of Write	t_{CW}	75	-	85	-	100	-	ns
Address Valid to End of Write	t_{AW}	75	-	85	-	100	-	ns
Address Setup Time	t_{AS}	0	-	0	-	0	-	ns
Write Pulse Width	t_{WP}	65	-	75	-	85	-	ns
Write Recovery Time	t_{WR}	0	-	0	-	0	-	ns
Write to Output in High Z (11)	t_{WHZ}	0	30	0	35	0	40	ns
Data to Write Time Overlap	t_{DW}	35	-	40	-	45	-	ns
Data Hold from Write Time	t_{DH}	0	-	0	-	0	-	ns
Output active from end of write (10)	t_{OW}	5	-	5	-	5	-	ns

Write Cycle No.1 Timing Waveform



Write Cycle No.2 Timing Waveform



AC Characteristics Notes

(1) A write occurs during the overlap (t_{WP}) of a low $\overline{CS}$ and a low $\overline{WE}$.

(2) t_{CW} is measured from the earlier of $\overline{CS}$ or $\overline{WE}$ going high to the end of write cycle.

(3) t_{AS} is measured from the address valid to the beginning of write.

(4) t_{WR} is measured from the earliest of $\overline{CS}$ or $\overline{WE}$ going high to the end of write.

(5) During this period, I/O pins are in the output state. Input signals out of phase must not be applied.

(6) If $\overline{CS}$ goes low simultaneously with $\overline{WE}$ going low or after $\overline{WE}$ going low , outputs remain in a high impedance state.

(7) D_{OUT} is in the same phase as written data of this write cycle.

(8) D_{OUT} is the read data of next address.

(9) If $\overline{CS}$ is low during this period, I/O pins are in the output state, and inputs out of phase must not be applied to I/O pins.

(10) This parameter is sampled and not 100% tested.

(11) t_{WHZ} is defined as the time at which the outputs achieve open circuit conditions and is not referenced to output voltage levels. This parameter is sampled and not 100% tested.

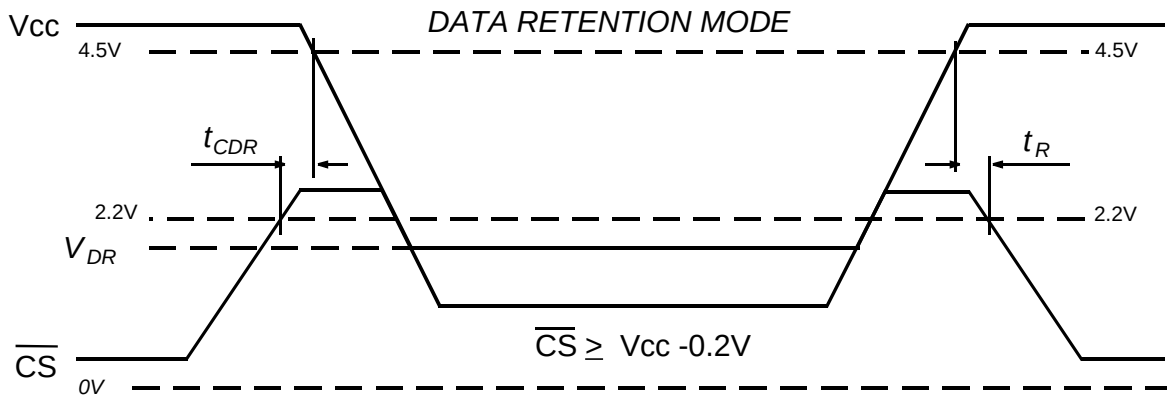
Low V_{cc} Data Retention Characteristics - L Version Only (T_A = 0°C to +70°C)

Parameter	*Sym*	*Test Condition*	*min*	*-L Part typ(1)*	*max*	*Unit*
V_{CC} for Data Retention	V_{DR}	$\overline{CS}$=V_{CC}-0.2V	2.0	-	-	V
Data Retention Current	I_{CCDR1} (2)	V_{CC} = 3.0V, $\overline{CS}$ = V_{CC}-0.2V, A17~A19 = V_{CC}-0.2V or 0.2V	-	-	400	mA
Data Retention Time	t_{CDR}	See Retention Waveform	0	-	-	ns
Operation Recovery Time	t_R	See Retention Waveform	5	-	-	ms

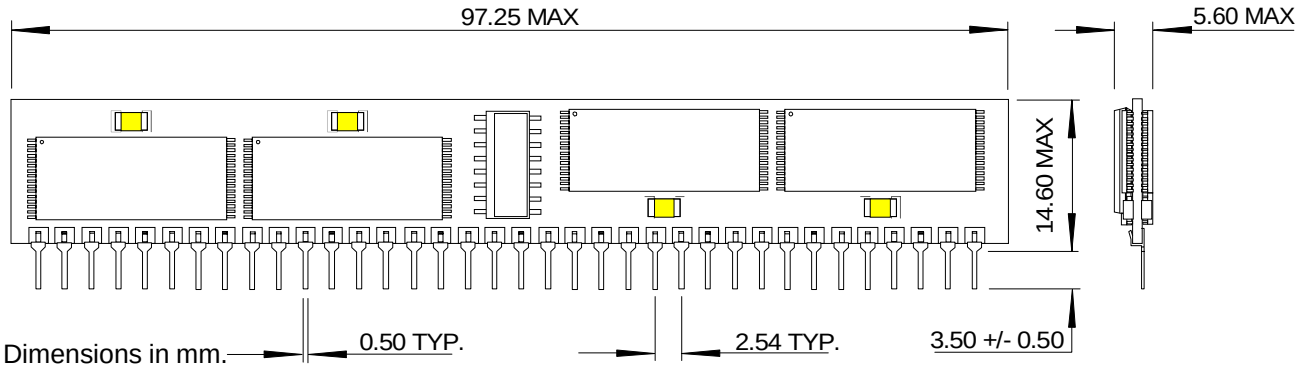
Notes (1) Typical figures are measured at 25°C.

(2) This parameter is guaranteed not tested.

Data Retention Waveform



Package Information



Ordering Information

SYS81000RKXLI - 10

Speed	85	=	85 ns
	10	=	100 ns
	12	=	120 ns
Temperature Range	Blank	=	Commercial Temperature
	I	=	Industrial Temperature
Power Consumption	Blank	=	Standard Part
	L	=	Low Power Part
Package	RKX	=	Plastic 36 pin SIL
Organization	81000	=	1M x 8
Memory Type	SYS	=	Static RAM

Note :

Although this data is believed to be accurate, the information contained herein is not intended to and does not create any warranty of merchantibility or fitness for a particular purpose.

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